

# SURFBOARDS®



THE BREADBOARDING MEDIUM FOR **SURFACE MOUNT™**

## 33000 SERIES APPLICATION SPECIFIC ADAPTERS

IDS33003

REV 1-2012

MODEL **33003**

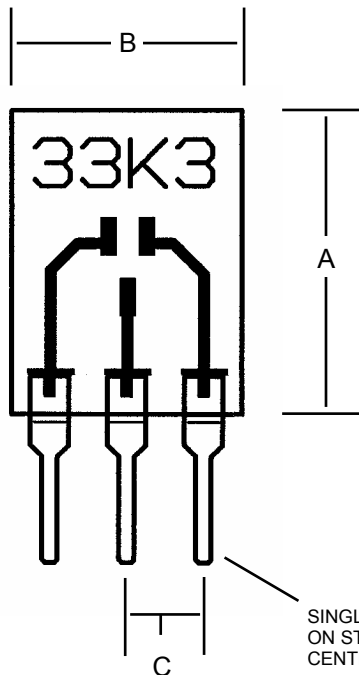
**ACCEPTS**  
(PARTIAL LISTING)

**SC-70-3**  
**SOT-323**  
**ANALOG KS-3**  
**CENTRAL SUPERMINI™ \***  
**DOIDES INC. DFN322 \*1**  
**NEC PKG No. 30**  
**ON SEMI CASE 419-AB-01**  
**RENESAS SSP**  
**TOSHIBA UFM / USM**

ALWAYS CONSULT DEVICE DATA SHEET TO INSURE PROPER FIT

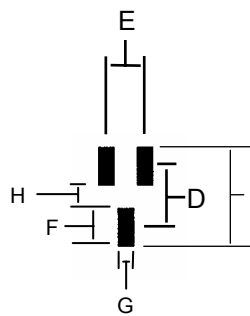
PINS ON .100 in. CENTERS  
PROVIDE COMPATIBILITY WITH  
CONVENTIONAL AND  
SOLDERLESS BREADBOARDS AND  
SOCKETS.

USE FOR PROTOTYPING,  
DEVICE TEST OR EVALUATION,  
SMD TO THROUGH HOLE  
CONVERSION



SEE WEBSITE FOR  
SOLDERING  
SUGGESTIONS

DEVICE FOOTPRINT



SINGLE-IN-LINE (SIP) PINS  
ON STANDARD .100 IN.  
CENTERS. SEE PIN SPECS.

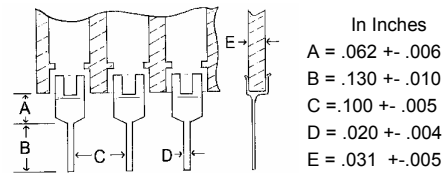
FIG.	INCHES	MM	NOTE:
A	.400	10.16	BOARD HEIGHT +/- .5mm .020in.
B	.300	7.62	BOARD WIDTH +/- .5mm .020in.
C	.100	2.54	SIP PIN SPACE +/- .20mm .008in.
D	.080	2.03	PAD CENTERLINE
E	.0512	1.30	DEVICE LEAD PITCH
F	.050	1.27	PAD LENGTH
G	.020	.508	PAD WIDTH
H	.030	.76	GAP
I	.130	3.30	MAX LEAD WIDTH

NOTE \*1  
This device  
must be  
mounted  
offset to  
avoid  
shorting of  
pads.



\* Supermini is a  
Trademark of Central  
Semiconductor Corp.

### PIN SPECIFICATIONS / TOLERANCES



In Inches  
A = .062 +/- .006  
B = .130 +/- .010  
C = .100 +/- .005  
D = .020 +/- .004  
E = .031 +/- .005

### BOARD SPECIFICATIONS

**BOARD MATERIAL:** .8mm, +/- .13mm .031in+/- .005 in.  
Thick G-10 FR-4 Glass Epoxy or equivalent.  
**CIRCUITS:** 1 oz. Copper with RoHS compliant Lead  
Free solder coating. Patten Position on board +/-  
.5mm .020in.

**TOLERANCES:** If not noted are +/- 20%. Nominal values are given.  
Controlling unit is Millimeters. Values rounded to nearest decimal. Slight  
Variations due to manufacturing process can occur.

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